



ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES

3000 Lakeside Dr.
Bannockburn, IL 60015

IPC-TM-650 TEST METHODS MANUAL

2.5.1B Arc Resistance of Printed Wiring Material

2.5.2A Capacitance of Insulating Materials

2.5.3B Current Breakdown, Plated-Through Holes

2.5.4 Current Carrying Capacity, Multilayer Printed Wiring

2.5.4.1A Conductor Temperature Rise Due to Current Changes in Conductors

2.5.5A Dielectric Constant of Printed Wiring Materials

2.5.5.1B Permittivity (Dielectric Constant) and Loss Tangent (Dissipation Factor) of Insulating Material at 1 MHz (Contacting Electrode Systems)

2.5.5.2A Dielectric Constant and Dissipation Factor of Printed Wiring Board Material—Clip Method

2.5.5.3C Permittivity (Dielectric Constant) and Loss Tangent (Dissipation Factor) of Materials (Two Fluid Cell Method)

2.5.5.4 Dielectric Constant and Dissipation Factor of Printed Wiring Board Material—Micrometer Method

2.5.5.5C Stripline Test for Permittivity and Loss Tangent (Dielectric Constant and Dissipation Factor) at X-Band

2.5.5.5.1 Stripline Test for Complex Relative Permittivity of Circuit Board Materials to 14 GHz

2.5.5.6 Non-Destructive Full Sheet Resonance Test for Permittivity of Clad Laminates

2.5.5.7A Characteristic Impedance and Time Delay of Lines on Printed Boards by TDR

2.5.5.8 Low Frequency Dielectric Constant and Loss Tangent, Polymer Films

Number 2.5	
Subject Electrical Test Methods	
Date 12/07	Revision X
Originating Task Group	

2.5.5.9 Permittivity and Loss Tangent, Parallel Plate, 1 MHz to 1.5 GHz

2.5.5.10 High Frequency Testing to Determine Permittivity and Loss Tangent of Embedded Passive Materials

2.5.5.13 Relative Permittivity and Loss Tangent Using a Split-Cylinder Resonator

2.5.6B Dielectric Breakdown of Rigid Printed Wiring Material

2.5.6.1B Solder Mask - Dielectric Strength

2.5.6.2A Electric Strength of Printed Wiring Material

2.5.6.3 Dielectric Breakdown Voltage and Dielectric Strength

2.5.7D Dielectric Withstanding Voltage, PWB

2.5.7.1 Dielectric Withstanding Voltage, Polymeric Conformal Coating

2.5.7.2 Dielectric Withstanding Voltage (HiPot Method) - Thin Dielectric Layers for Printed Circuit Boards (PCBs)

2.5.8A Dissipation Factor of Flexible Printed Wiring Material

2.5.10.1 Insulation Resistivity for Adhesive Interconnection Bonds

2.5.12 Interconnection Resistance, Multilayer Printed Wiring

2.5.13A Resistance of Copper Foil Wiring

2.5.14A Resistivity of Copper Foil

2.5.15A Guidelines and Test Methods for RFI-EMI Shielding of Flat Cable

2.5.16A Shorts, Internal on Multilayer Printed Wiring

2.5.17E Volume Resistivity and Surface Resistance of Printed Wiring Materials

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Documents
Page 1 of 2
Document Sharing Hub

IPC-TM-650		
Number 2.5	Subject Electrical Test Methods	Date 12/07
Revision X		

2.5.17.1A Volume and Surface Resistivity of Dielectric Materials

2.5.17.2 Volume Resistivity of Conductive Materials Used in High Density Interconnection (HDI) and Microvias, Two-Wire Method

2.5.18B Characteristic Impedance Flat Cables (Unbalanced)

2.5.19A Propagation Delay of Flat Cables Using Time Domain Reflectometer

2.5.19.1A Propagation Delay of Flat Cables Using Dual Trace Oscilloscope

2.5.21A Digital Unbalance Crosstalk, Flat Cable

2.5.24 Conductor Resistance, Flexible Flat Cable

2.5.25A Dielectric Withstand Voltage Flexible Flat Cable

2.5.26A Insulation Resistance, Flexible Flat Cable

2.5.27 Surface Insulation Resistance of Raw Printed Wiring Board Material

2.5.28A Q Resonance, Flexible Printed Wiring Materials

2.5.30 Balanced and Unbalanced Cable Attenuation Measurements

2.5.31 Current Leakage (Through Overglaze Films)

2.5.32 Resistance Test, Plated-Through Holes

2.5.33 Measurement of Electrical Overstress from Soldering Hand Tools

2.5.33.1 Measurement of Electrical Overstress from Soldering Hand Tools - Ground Measurements

2.5.33.2 Measurement of Electrical Overstress from Soldering Hand Tools - Transient Measurements

2.5.33.3 Measurement of Electrical Overstress from Soldering Hand Tools - Current Leakage Measurements

2.5.33.4 Measurement of Electrical Overstress from Soldering Hand Tools - Shielded Enclosure